SN5406, SN5416, SN7406, SN7416 HEX INVERTER BUFFERS/DRIVERS WITH OPEN-COLLECTOR HIGH-VOLTAGE OUTPUTS

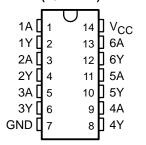
SDLS031A - DECEMBER 1983 - REVISED DECEMBER 2001

- Convert TTL Voltage Levels to MOS Levels
- High Sink-Current Capability
- Input Clamping Diodes Simplify System Design
- Open-Collector Drivers for Indicator Lamps and Relays
- Inputs Fully Compatible With Most TTL Circuits

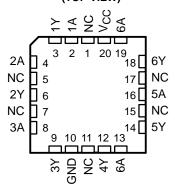
description

These TTL hex inverter buffers/drivers feature high-voltage open-collector outputs for interfacing with high-level circuits (such as MOS) or for driving high-current loads (such as lamps or relays), and also are characterized for use as inverter buffers for driving TTL inputs. The SN5406 and SN7406 have minimum breakdown voltages of 30 V. The SN5416 and SN7416 have minimum breakdown voltages of 15 V. The maximum sink current is 30 mA for the SN5406 and SN5416, and 40 mA for the SN7406 and SN7416.

SN5406, SN5416 . . . J OR W PACKAGE SN7406 . . . D, N, OR NS PACKAGE SN7416 . . . D OR N PACKAGE (TOP VIEW)



SN5406 . . . FK PACKAGE (TOP VIEW)



NC - No internal connection

ORDERING INFORMATION

TA	PAC	(AGE [†]	ORDERABLE PART NUMBER	TOP-SIDE MARKING	
		Tube	SN7406D	7406	
	SOIC – D	Tape and reel	SN7406DR	7400	
	30IC - D	Tube	SN7416D	7416	
0°C to 70°C		Tape and reel	SN7416DR	1410	
	PDIP – N	Tube	SN7406N	SN7406N	
	PDIP – N	Tube	SN7416N	SN7416N	
	SOP – NS	Tape and reel	SN7406NSR	SN7406	
–55°C to 125°C	CDIP – J	Tube	SNJ5406J	SNJ5406J	
	CDIP – J	Tube	SNJ5416J	SNJ5416J	
	CDIP – W	Tube	SNJ5406W	SNJ5406W	
	CDIF - W	Tube	SNJ5416W	SNJ5416W	
	LCCC – FK Tube		SNJ5406FK	SNJ5406FK	

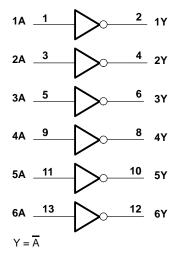
[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



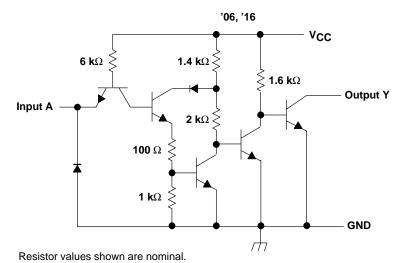
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logic diagram (positive logic)



schematic (each buffer/driver)



absolute maximum ratings over operating free-air temperature (unless otherwise noted)

Supply voltage, V _{CC} (see Note 1)	7 V
Input voltage, V _I (see Note 1)	
Output voltage, VO (see Notes 1 and 2): SN5406, SN7406	
SN5416, SN7416	15 V
Package thermal impedance, θ _{JA} (see Note 3): D package	86°C/W
N package	80°C/W
NS package	76°C/W
Storage temperature range, T _{eta}	65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. Voltage values are with respect to network ground terminal.
 - 2. This is the maximum voltage which should be applied to any output when it is in the off state.
 - 3. The package thermal impedance is calculated in accordance with JESD 51-7.



SDLS031A - DECEMBER 1983 - REVISED DECEMBER 2001

recommended operating conditions

				SN5406 SN5416			SN7406 SN7416		
			MIN	NOM	MAX	MIN	NOM	MAX	
VCC	V _{CC} Supply voltage		4.5	5	5.5	4.75	5	5.25	V
VIH	H High-level input voltage		2			2			V
V _{IL}	Low-level input voltage				0.8			0.8	V
\/a	High-level output voltage	'06			30			30	V
VOH	nigh-level output voltage	'16			15			15	V
lOL	I _{OL} Low-level output current				30			40	mA
TA	Operating free-air temperature		-55		125	0		70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS†				SN5406 SN5416			SN7406 SN7416		
		MIN	TYP‡	MAX	MIN	TYP‡	MAX			
V _{IK}	$V_{CC} = MIN,$	I _I = -12 mA				-1.5			-1.5	V
^I ОН	$V_{CC} = MIN,$	$V_{IL} = 0.8 V$,	V _{OH} = §			0.25			0.25	mA
V _{OL}	V _{CC} = MIN,	V _{IH} = 2 V	I _{OL} = 16 mA			0.4			0.4	V
			I _{OL} = ¶			0.7			0.7	V
Ц	$V_{CC} = MAX$,	V _I = 5.5 V				1			1	mA
lін	$V_{CC} = MAX$,	V _{IH} = 2.4 V				40			40	μΑ
I _{IL}	$V_{CC} = MAX$,	$V_{IL} = 0.4 V$				-1.6			-1.6	mA
Іссн	V _{CC} = MAX				30	48		30	48	mA
ICCL	V _{CC} = MAX	_			32	51		32	51	mA

[†] For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

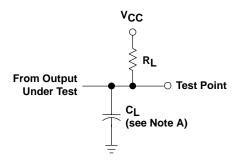
switching characteristics, V_{CC} = 5 V, T_A = 25°C (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS	MIN	TYP	MAX	UNIT
t _{PLH}	۸	Y	$R_L = 110 \Omega$, $C_L = 15 pF$		10	15	ns
tPHL	A				15	23	115

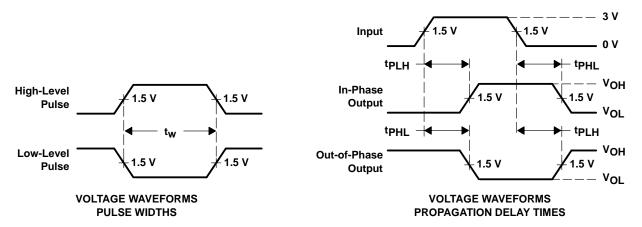


[‡] All typical values are at V_{CC} = 5 V, T_A = 25°C. § V_{OH} = 30 V for '06 and 15 V for '16. ¶ I_{OL} = 30 mA for SN54' and 40 mA for SN74'.

PARAMETER MEASUREMENT INFORMATION



LOAD CIRCUIT



NOTES: A. C_L includes probe and jig capacitance.

- B. In the examples above, the phase relationships between inputs and outputs have been chosen arbitrarily.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 1 MHz, $Z_O = 50 \Omega$, $t_f \leq$ 7 ns.
- D. The outputs are measured one at a time with one input transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms







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PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
JM38510/00801BCA	ACTIVE	CDIP	J	14	1	None	Call TI	Level-NC-NC-NC
JM38510/00801BDA	ACTIVE	CFP	W	14	1	None	Call TI	Level-NC-NC-NC
SN5406J	ACTIVE	CDIP	J	14	1	None	Call TI	Level-NC-NC-NC
SN5416J	ACTIVE	CDIP	J	14	1	None	Call TI	Level-NC-NC-NC
SN7406D	ACTIVE	SOIC	D	14	50	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR/ Level-1-235C-UNLIM
SN7406DR	ACTIVE	SOIC	D	14	2500	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR/ Level-1-235C-UNLIM
SN7406J	OBSOLETE	CDIP	J	14		None	Call TI	Call TI
SN7406N	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
SN7406N3	OBSOLETE	PDIP	N	14		None	Call TI	Call TI
SN7406NSR	ACTIVE	SO	NS	14	2000	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR/ Level-1-235C-UNLIM
SN7416D	ACTIVE	SOIC	D	14	50	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR/ Level-1-235C-UNLIM
SN7416DR	ACTIVE	SOIC	D	14	2500	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR/ Level-1-235C-UNLIM
SN7416N	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
SN7416N3	OBSOLETE	PDIP	N	14		None	Call TI	Call TI
SN7416NSR	ACTIVE	SO	NS	14	2000	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR/ Level-1-235C-UNLIM
SNJ5406FK	ACTIVE	LCCC	FK	20	1	None	Call TI	Level-NC-NC-NC
SNJ5406J	ACTIVE	CDIP	J	14	1	None	Call TI	Level-NC-NC-NC
SNJ5406W	ACTIVE	CFP	W	14	1	None	Call TI	Level-NC-NC-NC
SNJ5416J	ACTIVE	CDIP	J	14	1	None	Call TI	Level-NC-NC-NC
SNJ5416W	ACTIVE	CFP	W	14	1	None	Call TI	Level-NC-NC-NC

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - May not be currently available - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

None: Not yet available Lead (Pb-Free).

Pb-Free (**RoHS**): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

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(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDECindustry standard classifications, and peak solder temperature.

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PACKAGE OPTION ADDENDUM

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